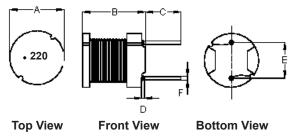
# Inductor **Radial Leaded**

**RoHS** 

Compliant



### **Configurations and Dimensions**



Note : White dot of marking indicates the start terminal of winding

### T

Fest Data for Mechanical						
Test Item	A mm	B mm	C mm	D mm	E mm	F mm
Specification	7.8 ±0.5	9.5 ±0.5	5 ±1	2 (Max.)	5 ±0.5	Ø0.7 (Ref.)
1	7.83	9.41	5.07	1.52	4.92	0.68
2	7.88	9.44	5.12	1.53	4.95	0.67
3	7.85	9.45	5.15	1.22	4.92	0.66
4	7.82	9.44	5.08	1.12	4.98	0.67
5	7.83	9.53	5.09	1.23	5.01	0.68
Average	7.84	9.45	5.1	1.32	4.96	0.67

### **Electrical Characteristics**

Test Condition		
1kHz 0.25V	L	22µH ±10%
TA = 25°C	DCR	65mΩ (Max)
1kHz 0.25 V Irms = 2.3A	ΔΤ	Temperature rise 40°C (Max.)

Operating temperature : -55°C to +130°C

### Material List

No.	ltem	Item Material Description		
1	Core	F4F DR2W7.8 × 9.5 (SW) RCH B4.0 F5.4 P5		
2	Wire	Ø0.45mm UEFN/U (155°C)		
3	Solder (Lead-free)	Sn99.3% / Cu0.7%		

Newark.com/multicomp-pro Farnell.com/multicomp-pro Element14.com/multicomp-pro



Schematic Diagram



Note:

1. Wire UEFN/U (155°C) Ø0.45mm

2. 26.5TS (Reference) C.W

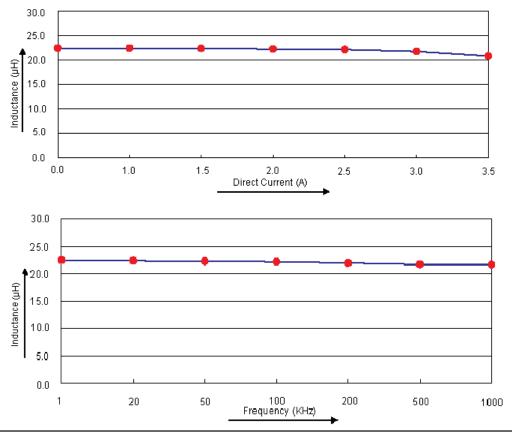
#### 15/11/19 V1.0

# Inductor Radial Leaded

### **Reliability Test**

Test Item	Specifications		Test Method and Remarks		
Operating temperature range	-55°C to +130°C		Including temperature	rise due to self-generated heat.	
Storage condition	Ambient temperature: 0°C to 40°CHumidity: Below 70% RH		To maintain the solderability of terminal electrodes, care must be taken to control temperature and humidity in the storage area.		
Moisture sensitivity	Appearance DCR change Inductance change	: No abnormality No damage : Within ±5% : Within ±5%	According to J-STD-02 Test condition Test duration Recovery	<ul> <li>0B level 3</li> <li>: 60°C 60% RH</li> <li>: 40 hrs</li> <li>: 1 to 2 hours of recovery under the standard condition after the removal from the test chamber.</li> </ul>	
Solderability	All termination shall exhibit a continuous solder coating free from defects for a minimum of 95% of the surface area of any individual lead.		According to J-STD-00 Steam aging category Steam aging duration Solder Solder temperature Dip time	: 97°C 98% RH	

### **Electric Characteristics**



Newark.com/multicomp-pro Farnell.com/multicomp-pro Element14.com/multicomp-pro



# multicomp PRO

### **Test Data for Electrical**

Test Item	L µH	DCR Ω	ΔΤ
Condition	1kHz 0.25V	at 25°C	1kHz 0.25V Irms = 2.3A
Specification	22 ±10%	65 (Max.)	Temperature rise 40°C (Max.)
1	22.6	47.88	
2	22.46	47.49	
3	22.4	47.96	OK
4	22.38	48.03	
5	22.48	47.96	
Average	22.46	47.86	OK

#### **Part Number Table**

Description	Part Number	
Inductor, 22µH, 10%, Radial Leaded	MCSCH895-220KU	

Important Notice : This data sheet and its contents (the "Information") belong to the members of the AVNET group of companies (the "Group") or are licensed to it. No licence is granted for the use of it other than for information purposes in connection with the products to which it relates. No licence of any intellectual property rights is granted. The Information is subject to change without notice and replaces all data sheets previously supplied. The Information supplied is believed to be accurate but the Group assumes no responsibility for its accuracy or completeness, any error in or omission from it or for any use made of it. Users of this data sheet should check for themselves the Information and the suitability of the products for omitted. Liability for loss or damage resulting from any reliance on the Information or use of it (including liability resulting from negligence or where the Group was aware of the possibility for such as or damage arising) is excluded. This will not operate to limit or restrict the Group's liability for death or personal injury resulting from its negligence. Multicomp Pro is the registered trademark of Premier Farnell Limited 2019.

Newark.com/multicomp-pro Farnell.com/multicomp-pro Element14.com/multicomp-pro

